Build Up HDI (Standard)

HDI10_2+6b+2_1,50_35_engl

10 - Layers

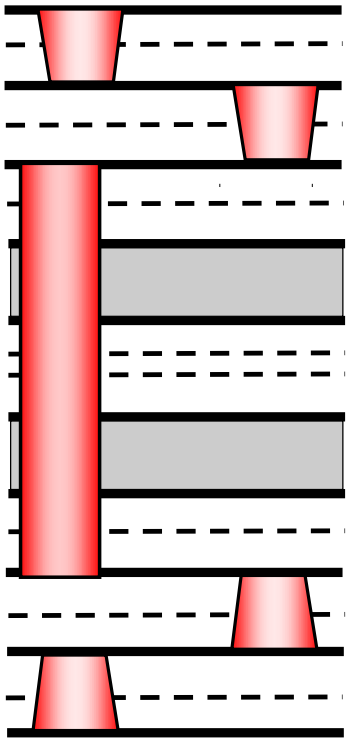
Core: 0,36 mm Cu 35/35 µm

WE-Articel No.:

2 + 6B + 2

Customer:

WÜRTH ELEKTRONIK



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		30	
					1 x 1080	60	
	3		Foil	9 µm		30	
					1 x 1080	60	
	4			35 µm		33	
			0,360 mm			360	
	5			35 µm		33	
					2 x 1080	124	
	6			35 µm		33	
			0,360 mm			360	
	7			35 µm		33	
					1 x 1080	60	
	8		Foil	9 µm		30	
					1 x 1080	60	
	9		Foil	12 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	
			1) copper thickness outer layers: appr. 55 µm				
			total material thickness:			1480	
			Note: Lamination thickness for Prepregs depending on layout characteristics.				

final lamination thickness:	**1,48**	+/-	0,13	mm			Date:	Engineer:
thickness with electro plated Cu:	1,57	+/-	0,16	mm				
total thickness with soldermask	1,63	+/-	0,18	mm				
customer requirement		+/-		mm	point:			

prepared:		checked:		approved:			
on	by	on	by	on	by	revision	
28.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00	page: 19+